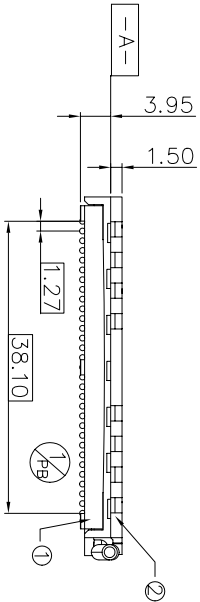
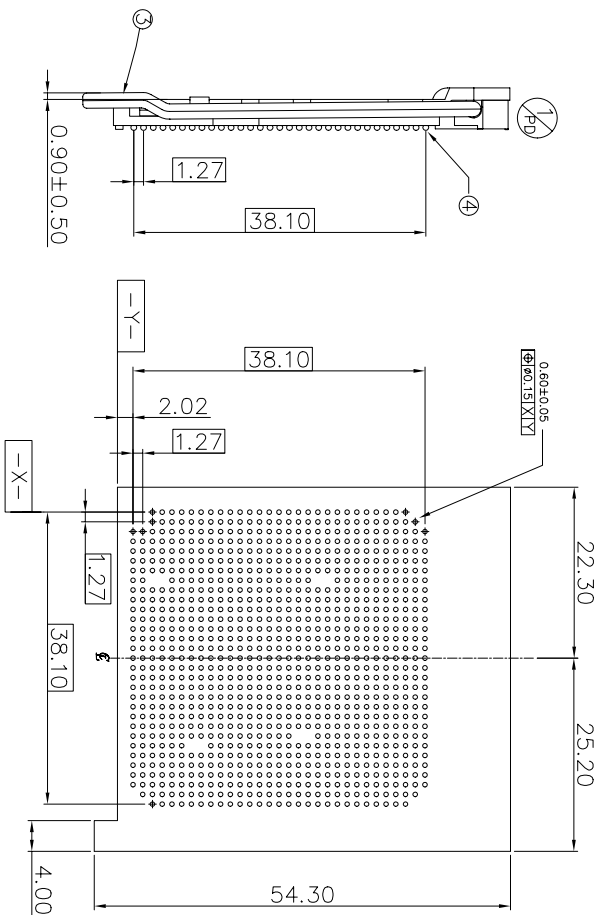
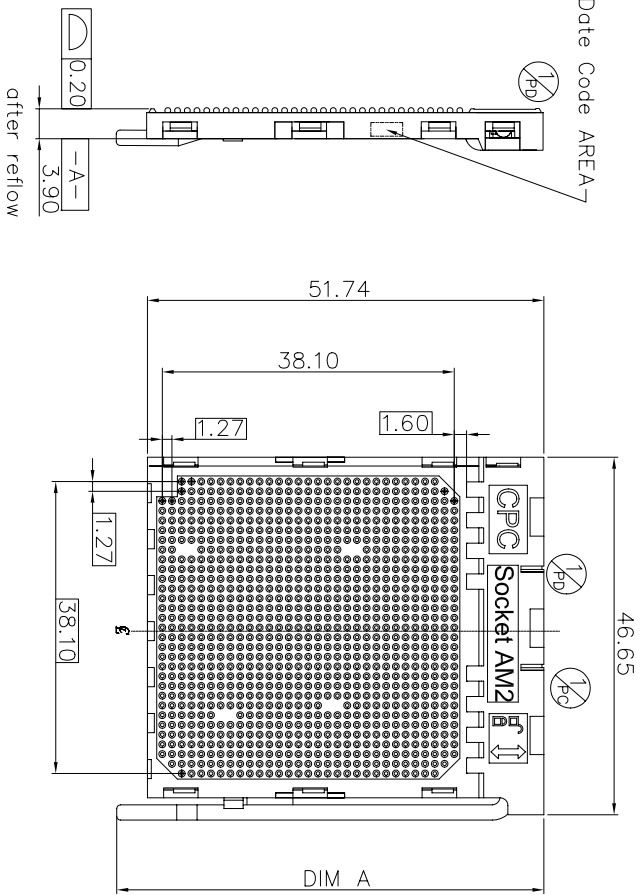




**RoHS Compliant**  
2002/95/EC

Date Code AREA



1 Dimensional Information

SUYIN P/NO	DIM. A
127091FK940JX00PY	53.93
127091FK940JX01PY	55.73

1. 127091FK940JX00PY
- F: Selective plating
- J1-05μ\*Min. Gold in contact area.
  - J2-Gold flash in contact area.
  - J3-10μ\*Min. Gold in contact area.
  - J4-15μ\*Min. Gold in contact area.
  - J5-30μ\*Min. Gold in contact area.

RECOMMENDED P.C BOARD LAYOUT

5	TERMINAL	Copper Alloy	GOLD PLATED OVER IN
4	Solder Ball	Solder Alloy Composition	
3	HANDLE	Stainless Steel	
2	COVER	High Temp. Plastic	UL 94V-0
1	BASE	High Temp. Plastic	UL 94V-0
NO. DESCRIPTION		MATERIAL	COLOR
			REMARK

**SUYIN**  
CONNECTOR

CUSTOMER TITLE: Socket AM2 Solder Ball Type

COPY: 127091FK940JX00PY

PART NO. (OLD):

FILE NAME: C 127091FK940JX00PY-00C

SCALE: 1:1 UNIT: mm SHEET: 1 of 1

**SOCKET DEP**

PE 01/05/07	PE 1: 新增成品料號	Angle	±2°	DRAW	吳玉明	07/30/05
PD 10/18/06	PD 1: 修改圖面與實物相符	X.	±0.50	DESIGN	吳玉明	07/30/05
PC 05/01/06	PC 1: 修改刻字符號	X.X	±0.25	CHECK	范政徽	07/30/05
PB 12/13/05	修改標注	X.XX	±0.15	APPRO.	范政徽	07/30/05
ECN(DCN) NO.	REV	DATE	DESCRIPTION	CHANGE	APPRO.	GENERAL TOLERANCE UNLESS OTHERWISE NOTED